

Nobuhiko Chiwata

List of Publications by Year in descending order

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citing authors

#	ARTICLE	IF	CITATIONS
1	Development of Fe-based high Bs nanocrystalline alloy powder. Journal of Magnetism and Magnetic Materials, 2020, 509, 166838.	2.3	7
2	Thermal Deformation Analysis of Ceramic Substrate with Thick Cu Layer. Journal of Japan Institute of Electronics Packaging, 2019, 22, 112-118.	0.1	0
3	625 Deformation Behavior of Ceramic Substrate with Thick Cu Layer in Joining Process. The Proceedings of the Materials and Processing Conference, 2015, 2015.23, _625-1_-_625-3_.	0.0	0
4	207 Thermal Deformation Mechanism of Ceramic Substrate for Next-generation Power Semiconductor Modules. The Proceedings of Ibaraki District Conference, 2015, 2015.23, 109-110.	0.0	0
5	Basic Study on Electromigration Phenomena in Pb-free Solder Joint. Journal of Japan Institute of Electronics Packaging, 2013, 16, 159-163.	0.1	0
6	Electromigration failure analysis of flip-chip solder joint by using void growth simulation and synchrotron radiation X-ray microtomography. , 2012, , .		1
7	Current density redistribution from no current crowding to current crowding in Pb-free solder joints with an extremely thick Cu layer. Acta Materialia, 2012, 60, 102-111.	7.9	17
8	Void Growth Analysis of Flip-Chip Solder Joint by Using Electromigration Failure Simulation and Synchrotron Radiation X-Ray Microtomography. Journal of Japan Institute of Electronics Packaging, 2012, 15, 541-549.	0.1	0
9	Use of Modified Accumulated Damage Model to Predict Fatigue Failure Lives of Sn-Ag-Cu-based Solder Joints in Ball-Grid-Array-Type Packages. Transactions of the Japan Institute of Electronics Packaging, 2012, 5, 1-11.	0.4	3
10	205 Electromigration Clarification of Micro-Solder Joint in Semiconductor Structure by using Synchrotron Radiation X-Ray Microtomography. The Proceedings of Ibaraki District Conference, 2012, 2012.20, 41-42.	0.0	0
11	Development of Highly Reliable BGA and Flip-Chip Structures by Using Cu-Cored Solder Ball. , 2011, , .		2
12	Electromigration in Copper-Core Solder Ball Joints During Thermal Cycle Tests. , 2011, , .		0
13	Use of Modified Accumulated Damage Model to Predict Fatigue Failure-life of Sn-Ag-Cu Based Solder Joints in Ball-Grid-Array-Type Packages. Journal of Japan Institute of Electronics Packaging, 2011, 14, 287-295.	0.1	0
14	Fracture Life Evaluation of Cu-Cored Solder Joint in BGA Package. , 2009, , .		3
15	718 Crack Propagation Analysis of Cu-cored Solder Joint. The Proceedings of the Computational Mechanics Conference, 2008, 2008.21, 311-312.	0.0	0